# MA2SD32

### Silicon epitaxial planar type

#### For super high speed switching

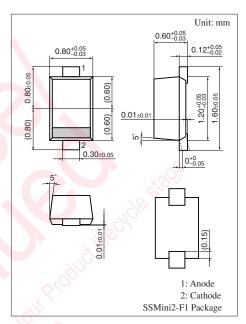
#### ■ Features

- $I_{F(AV)} = 200$  mA rectification is possible.
- Small reverse current:  $I_R < 5 \mu A$  (at  $V_R = 30 V$ )

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Repetitive peak reverse voltage	V <sub>RRM</sub>	30	V
Forward current (Average)	I <sub>F(AV)</sub>	200	mA
Peak forward current	$I_{FM}$	300	mA
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	1	A
Junction temperature	T <sub>j</sub>	125	°C
Storage temperature	$T_{\rm stg}$	-55 to +125	°C

Note) \*: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

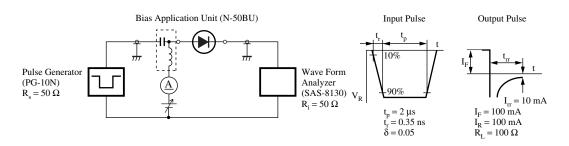


Marking Symbol: 8H

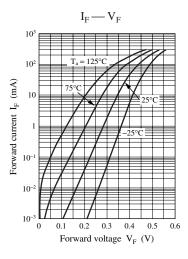
### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

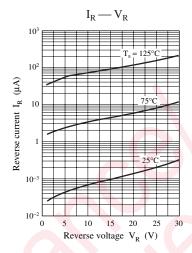
Parameter	Sy	mbol	Conditions	Min	Тур	Max	Unit
Reverse current		$I_{R1}$	$V_R = 10 \text{ V}$		10	0.5	μΑ
		$I_{R2}$	V <sub>R</sub> = 30 V	100	0	5	
Forward voltage		$V_{F}$	$I_F = 200 \text{ mA}$		0.49	0.56	V
Terminal capacitance	~;s <sup>C</sup>	Ct	$V_R = 0 V, f = 1 MHz$	1.90	25		pF
Reverse recovery time *		t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		2		ns
	Co.		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

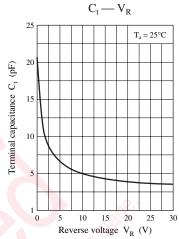
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. Absolute frequency of input and output is 250 MHz
  - 4. \*: t<sub>rr</sub> measurement circuit



## **Panasonic**







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